

**'98 マイクロマシン訪米調査団  
調査報告書**

**平成11年3月**

**財団法人マイクロマシンセンター**



## はじめに

マイクロマシン技術は次世代の基盤技術として注目されており、世界の大学、研究機関、あるいは企業において活発な研究開発が行われています。財団法人マイクロマシンセンターは1992年1月に設立以来、マイクロマシン技術の基盤を確立し、マイクロマシンが社会において広く普及することを目指して活動しています。

当センターの事業の一つに国際交流事業があり、その中核をなす一つとして海外への調査団の派遣があります。調査団は国際学会あるいは海外との交流セミナーに参加し、また同時に周辺研究機関を訪問し技術動向を調査すると共に、技術者間の交流を図ることを主たる目的としてきました。今回の調査団は、本年1月17日～21日にアメリカ・フロリダ州オーランドで開催された12th IEEE International Micro Electro Mechanical Systems Conference (MEMS'99)に参加すると共に、アメリカの研究機関を訪問しました。

MEMS'99の参加者は、529名（昨年のハイデルベルグMEMS'98は約670名）、発表件数は113件で、日本からの発表は30件と約1/4を占め、産技プロジェクト関係では6件の発表が行われました。主催国のアメリカ（48件）を除くと日本からの発表件数は群を抜いており、世界の中での日本のマイクロマシン技術が大きなウェイトを占めていることが分かりました。

調査団はMEMS'99に参加した後、ジョージア州アトランタにある Georgia Institute of Technology とカリフォルニア州バークレーにある University of California, Berkeley を訪問しました。訪問先では当センターの活動を紹介し、また訪問先の活動紹介を受け、更にこれらに関し活発な討論を行い、これらを通じて相互の技術交流を図ることができました。

この報告書は調査団のメンバーが分担して上記の調査内容をまとめたものです。この調査結果が参加した調査団員の今後の研究開発活動に生かされるだけでなく、マイクロマシンセンターの各種の事業活動に生かされることを願っています。また調査団員が11日間にわたって行動をともし、親交を深めたことは今後の研究開発の円滑な推進に大きく貢献することと期待する次第です。

最後に、団員各位のご協力と関係各位のご高配に深く感謝いたします。

平成11年3月

98マイクロマシン訪米調査団  
事務局  
(財団法人マイクロマシンセンター)

## 目 次

はじめに

### 1. 調査団概要

1. 1 調査団の構成	1
1. 2 調査日程	1
1. 3 調査研究機関	2

### 2. MEMS'99 概要報告

#### 2. 1 招待講演

(I-1) Structured Design of Integrated MEMS	4
(I-2) The Nanomechanical NOSE	5
(I-3) Neurointerface --- Interfaces of Neuronal Networks to Electrical Circuit ---	6

#### 2. 2 ポスター発表

##### 2. 2. 1 ACTUATORS

(P-AC-1) Micromachined Relay which Utilizes Single Crystal Silicon Electrostatic Actuator	8
(P-AC-2) A Fully-Packaged Electromagnetic Microrelay	9
(P-AC-3) Bent-Beam Electro-Thermal Actuators for High Force Applications	10
(P-AC-4) Soft Micromanipulation Devices with Multiple Degrees of Freedom Consisting of High Polymer Gel Actuators	11
(P-AC-5) Two-Dimensional Micro-Conveyer with Integrated Electrostatic Actuators	12

##### 2. 2. 2 AFM & DATA STORAGE

(P-AF-1) Low Voltage Driven Piggy-Back Actuator of Hard Disk Drives	13
(P-AF-2) MEMS Fabrication of High Aspect Ratio Track-Following Micro Actuator for Hard Disk Drive Using Silicon on Insulator	14

##### 2. 2. 3 INERTIAL SENSORS

(P-IS-1) A Surface Micromachined Silicon Gyroscope using a Thick Polysilicon Layer	15
(P-IS-2) Fabrication of Accelerometer using Single-Step Electrochemical Etching for Micro Structures (SEEMS)	16
(P-IS-3) Comparative Study of Novel Micromachined Accelerometers	

employing MIDOS	1 7
(P-IS-4) Presetable Micromachined MEMS Accelerometers	1 8
<b>2. 2. 4 PHYSICAL SENSORS</b>	
(P-PH-1) A Modular Integrated Pressure Control Unit for Gases	2 0
(P-PH-2) A Low Cost Batch-Sealed Capacitive Pressure Sensor	2 0
(P-PH-3) Direct Integration (DI) of Solid State Stress Sensors with Single Crystal Micro-Electro-Mechanical Systems for Integrated Displacement Sensing	2 1
<b>2. 2. 5 SENSORS</b>	
(P-SE-1) A Novel Micromachined Magnetic Field Sensor (MFS)	2 2
(P-SE-2) Direct-View Uncooled Micro-Optomechanical Infrared Camera	2 3
(P-SE-3) Spectral Infrared Absorption of CMOS Thin Film Stacks	2 4
(P-SE-4) Design and Fabrication of an Integrated Three-dimensional Tactile Sensor for Space Robotic Applications	2 4
<b>2. 2. 6 FLUIDIC SENSING &amp; CONTROL</b>	
(P-FL-1) A New Flow Sensor with High Time Resolution Based on Differential Pressure Principle	2 5
(P-FL-2) Three-Dimensional Sound Intensity Measurements Using Microflown Particle Velocity Sensors	2 5
(P-FL-3) An 8-Bit Microflow Controller Using Pneumatically-Actuated Microvalves	2 6
(P-FL-4) MEMS Based Transducers for Boundary Layer Control	2 7
(P-FL-5) Development of Bi-directional Valve-less Micropump for Liquid	2 8
(P-FL-6) A Practical Thermopneumatic Valve	2 9
<b>2. 2. 7 JETS &amp; FLUIDICS HANDLING</b>	
(P-JT-1) Flight Performance of Micro-wings Rotating in an Alternating Magnetic Field	3 0
(P-JT-2) A Microchannel Heat Sink with Integrated Temperature Sensors for Phase Transition Study	3 1
(P-JT-3) Micro Jet Array Heat Sink for Power Electronics	3 3
(P-JT-4) MEMS Impinging-Jet Micro Heat Exchanger	3 4
(P-JT-5) A Parylene Micro Check Valve	3 6
(P-JT-6) High Pressure Check Valve for Application in a Miniature Cryogenic Sorption Cooler	3 7
<b>2. 2. 8 MATERIALS &amp; FABRICATION</b>	
(P-MF-1) A New Chemical Grafting Material for Stiction Reduction	3 8
(P-MF-2) Direct Drawing for Microfabrication without Photolithography	3 9

(P-MF-3) Dendritic Materials as a Dry Release Sacrificial Layer . . .	4 0
(P-MF-4) A New Ultra-Hard Etch-Stop Layer for High Precision Micromachining . . . . .	4 1
(P-MF-5) Bosch Deep Silicon Etching: Improving Uniformity and Etch Rate for Advanced MEMS Applications . . . . .	4 2
<b>2. 2. 9 POLYMER MEMS</b>	
(P-P0-1) Cylindrical Plastic Lens Array Fabricated by a Micro Intrusion Process . . . . .	4 3
(P-P0-2) Re-Configurable Fluid Circuits by PDMS Elastomer Micromachining . . . . .	4 4
(P-P0-3) Silicon as Tool Material for Polymer Hot Embossing . . . . .	4 5
<b>2. 2. 10 3-D FABRICATION</b>	
(P-3D-1) Freeform Fabrication of Functional Microsolenoids, Microelectromagnets and Helical Springs Using High-Pressure Laser Chemical Vapor Deposition . . . . .	4 6
(P-3D-2) A Novel Micro Electro-Discharge Machining Method Using Electrodes Fabricated by the LIGA Process . . . . .	4 7
(P-3D-3) EFAB: Rapid, Low-Cost Desktop Micromachining of High Aspect Ratio True Three-D MEMS . . . . .	4 8
(P-3D-4) Moving Mask LIGA (M2LIGA) Process for Control of Side Wall Inclination . . . . .	4 9
<b>2. 2. 11 PACKAGING, BONDING &amp; CONNECTORS</b>	
(P-PK-1) Development of Microconnector with Automatic Connecting/Disconnecting Mechanism . . . . .	5 0
(P-PK-2) Micro IC Probe for LSI Testing . . . . .	5 0
(P-PK-3) Tantalum Oxide Thin Films as Protective Coating for Sensors . .	5 1
(P-PK-4) Flip-Chip Assembly for Si-Based RF MEMS . . . . .	5 1
(P-PK-5) A High Sensitivity Polyimide Humidity Sensor for Monitoring Hermetic Micropackages . . . . .	5 3
(P-PK-6) Localized Bonding with PSG or Indium Solder as Intermediate Layer . . . . .	5 4
(P-PK-7) The Surface Adhesion Parameter: A Measure for Wafer Bondability . . . . .	5 6
<b>2. 2. 12 MEASUREMENT, MODELING &amp; SIMULATION</b>	
(P-MS-1) Effect of Holes and Edges on the Squeeze Film Damping of Perforated Micromechanical Structures . . . . .	5 7
(P-MS-2) Nano-Meter Resolution of Three-Dimensional Motions Using	

	Video Interference Microscopy . . . . .	5 8
(P-MS-3)	Optimization of Sample Injection Components in Electrokinetic Microfluidic Systems . . . . .	5 9
(P-MS-4)	Comparison of Anisotropic Etching Properties between KOH and TMAH Solutions . . . . .	6 0
(P-MS-5)	Accurate Fully-Coupled Natural Frequency Shift of MEMS Actuators due to Voltage Bias and other External Forces . .	6 2
(P-MS-6)	Automated Optimal Synthesis of Microaccelerometers . . . .	6 3
(P-MS-7)	Simulation of Anisotropic Wet-Chemical Etching Using a Physical Model . . . . .	6 3
(P-MS-8)	Simple Modeling and Simulation of the Squeeze Film Effect and Transient Response of the MEMS Device . . . . .	6 5
<b>2. 2. 1 3 OPTICAL DEVICES</b>		
(P-OP-1)	Optically-Powered Optical Power Limiter for Use in Lightwave Networks . . . . .	6 6
(P-OP-2)	Highly Sensitive Optical Coherent Detection System using Surface Micromachining Technology . . . . .	6 6
(P-OP-3)	Fabrication of Optical Micro-Cantilever Consisting of Channel Waveguide for Scanning Near-Field Optical Microscopy Controlled by Atomic Force . . . . .	6 7
(P-OP-4)	A Novel Fabrication Method of the Tiny Aperture Tip on Si Cantilever for Near Field Scanning Optical Microscopy . . .	6 8
(P-OP-5)	Fabrication and Properties of Three-D Polysilicon Photonic Lattices in the Infrared . . . . .	6 9
(P-OP-6)	Self-Generated Light Emitting Device using Micromachined Si Mirror Array . . . . .	6 9
<b>2. 2. 1 4 MICRO REACTORS</b>		
(P-RE-1)	Micro Concentrator with Opto-sense Reactor for Biochemical IC Chip . . . . .	7 0
(P-RE-2)	Palladium Based Micromembranes for Hydrogen Separation and Hydrogenation/Dehydrogenation Reactions . . . . .	7 1
(P-RE-3)	Droplet-Based Nano/Picoliter Mixer Using Hydrophobic Microcapillary Vent . . . . .	7 3
(P-RE-4)	A Micro Reaction Tool for Heterogeneous Catalytic Gas Phase Reactions . . . . .	7 5
<b>2. 2. 1 5 バイオ分野への応用</b>		
(P-BI-1)	An Active Catheter with Integrated Circuit for Communication	

and Control	7 6
(P-B1-2) An Array of Hollow Microcapillaries for the Controlled Injection of Genetic Materials into Animal/Plant Cells	7 7
(P-B1-3) Development of a Microfine Active Bending Catheter Equipped with MIF Tactile Sensors	7 8
<b>2. 3 口頭発表</b>	
<b>2. 3. 1 オプティカル・デバイス</b>	
(S1-1) Multi-Element Thermo-Capillary Optical Switch and Sub-Nano Liter Oil Injection	7 9
(S1-2) A Low Voltage Micromachined Optical Switch by Stress-Induced Bending	8 2
(S1-3) A Micro-Sized Visual Sensor Based on a Fly's Compound Eye with a Scanning Retina	8 4
(S1-4) PZT Thin-Film Actuator Driven Micro Optical Scanning Sensor by Three-D Integration of Optical and Mechanical Devices	8 7
<b>2. 3. 2 アプリケーション</b>	
(S2-1) Micro-Actuators for Tera-Storage	8 8
(S2-2) Parallel Scanning AFM with On-Chip Circuitry in CMOS Technology	9 0
(S2-3) VHF Free-Free Beam High-Q Micromechanical Resonators	9 1
(S2-4) Pneumatically Driven Microcage for Micro-Objects in Biological Liquid	9 2
(S2-5) Three Dimensional SMA Microelectrodes with Clipping Structure for Insect Neural Recording	9 3
<b>2. 3. 3 パッケージングとボンディング</b>	
(S3-1) Vacuum Encapsulation of Resonant Devices using Permeable Polysilicon	9 6
(S3-2) A Batch Wafer Scale LIGA Assembly and Packaging Technique via Diffusion Bonding	9 8
(S3-3) Batch Micropackaging by Compression-Bonded Wafer-Wafer Transfer	1 0 0
(S3-4) Low Pressure and Low Temperature Hermetic Wafer Bonding using Microwave Heating	1 0 1
<b>2. 3. 4 圧力センサ</b>	
(S4-1) A Low Voltage Force-Balanced Pressure Sensor with Hermetically Sealed Servomechanism	1 0 2
(S4-2) Surface Micromachined Multi-layer Moving Gate Field Effect Transistor (MOGFET) Pressure Switch with Integrated Vacuum Sealed	

Cavity	104
(S4-3) Fabrication of Dome-Shaped Diaphragm with Circular Clamped Boundary on Silicon Substrate	106
(S4-4) Wireless Micromachined Ceramic Pressure Sensors	107
2. 3. 5 ジェットとフルイディクス・ハンドリング	
(S-5-1) Digital Micro Propulsion	108
(S-5-2) Polymer-Based Electro spray Chips for Mass Spectrometry	109
(S-5-3) Fabrication and Characterization of a Micro Turbine/Bearing Rig	110
(S-5-4) Manipulation of a Round Jet with Electromagnetic Flap Actuators	112
(S-5-5) A High-Performance Silicon Micropump for an Implantable Drug Delivery System	114
2. 3. 6 センサ	
(S-6-1) Micromachined CMOS Calorimetric Chemical Sensor with On-Chip Low Noise Amplifier	116
(S-6-2) A Micromachined Strain Sensor with Differential Capacitive Readout	117
(S-6-3) Quasi Monolithic Silicon Load Cell for Loads up to 1000 kg with Insensitivity to Non-homogeneous Load Distributions	118
(S-6-4) Microfabrication and Testing of 32 x 32 (1024) Cantilever Array Chip for AFM Storage	119
2. 3. 7 アクチュエータ	
(S-7-1) Prototype Microrobots for Micro Positioning in a Manufacturing Process and Micro Unmanned Vehicles	120
(S-7-2) A Robust Micro Conveyor Realized by Arrayed Polyimide Joint Actuators	120
(S-7-3) A Micromechanical Switch as the Logic Elements for Circuits in Multi Chip Module on Si (MCM-Si)	121
(S-7-4) Compliant Electro-Thermal Microactuators	122
(S-7-5) Magnetostatic MEMS Relays for the Miniaturization of Brushless DC Motor Controllers	123
2. 3. 8 慣性センサ	
(S-8-1) A High Sensitivity Capacitive Microaccelerometer with a Folded-Electrode Structure	124
(S-8-2) A Lateral Capacitive CMOS Accelerometer with Structural Curl Compensation	125



(S-8-3) The Symmetrical Z-Axis Gyroscope Having a High Aspect Ratio by a New and Simple Fabrication Process	1 2 6
(S-8-4) A Micromachined Vibrating Rate Gyroscope with Independent Beams for the Drive and Detection Modes	1 2 7
2. 3. 9 Alternative Materials & Fabrication	
(S-9-1) Monolithic Integration of Three-D Electroplated Microstructures of Unlimited Number of Levels Using Planarization with a Sacrificial Metallic Mold (PSMM)	1 3 0
(S-9-2) Post-CMOS Integration of Germanium Microstructures	1 3 1
(S-9-3) Application of Germanium to Low Temperature Micro-Machining	1 3 2
(S-9-4) Fabrication and Testing of Surface Micromachined SiC Micromotors	1 3 3
(S-9-5) Anisotropic Etching of Surfactant-Added TMAH Solution	1 3 4
3. 研究機関訪問	
3. 1 Georgia Institute of Technology	1 3 6
3. 2 University of California at Berkeley	1 4 1
あとがき	1 4 7